

FIG.1

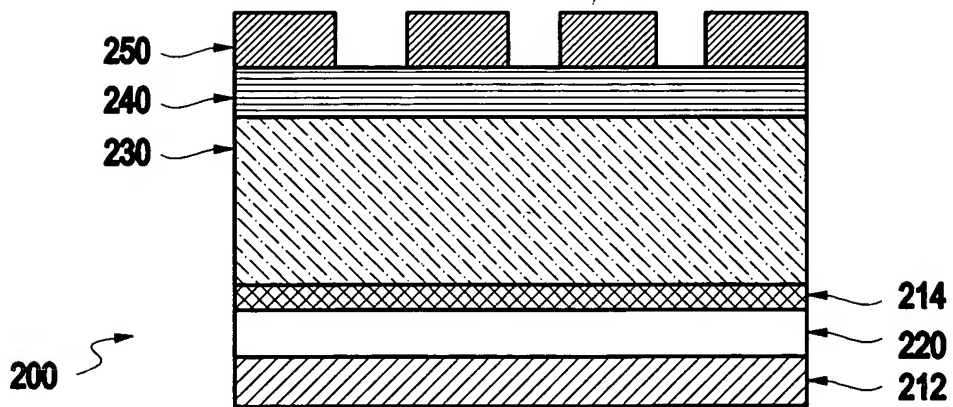


FIG.2

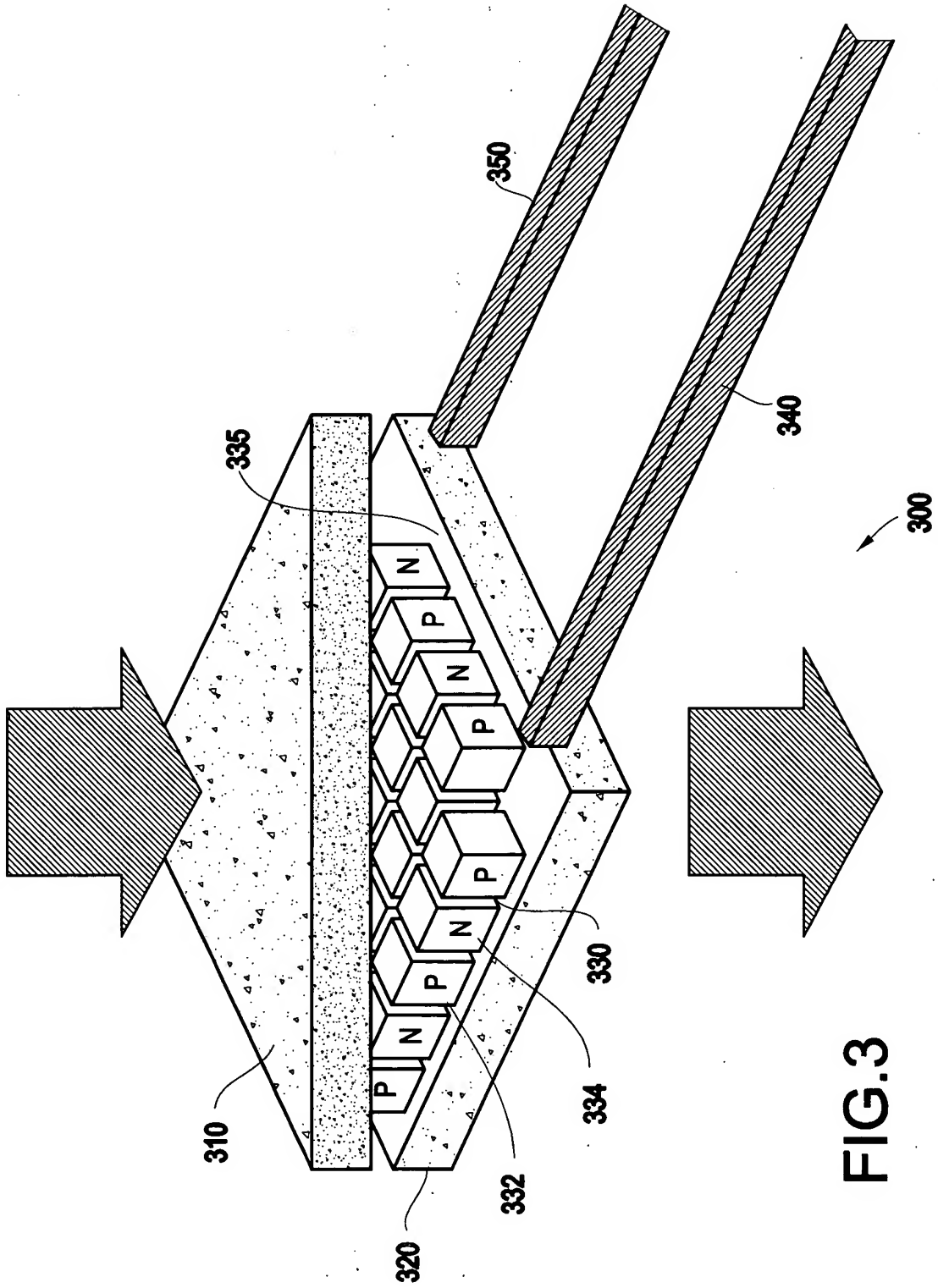


FIG. 3

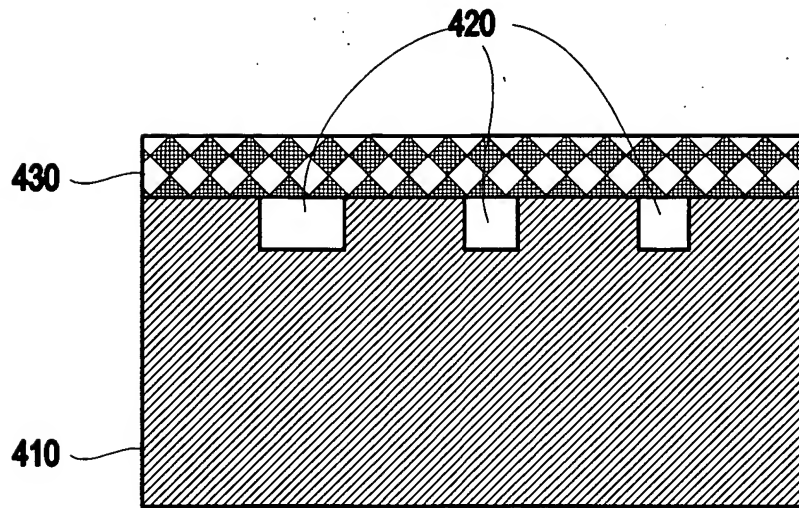


FIG.4

400

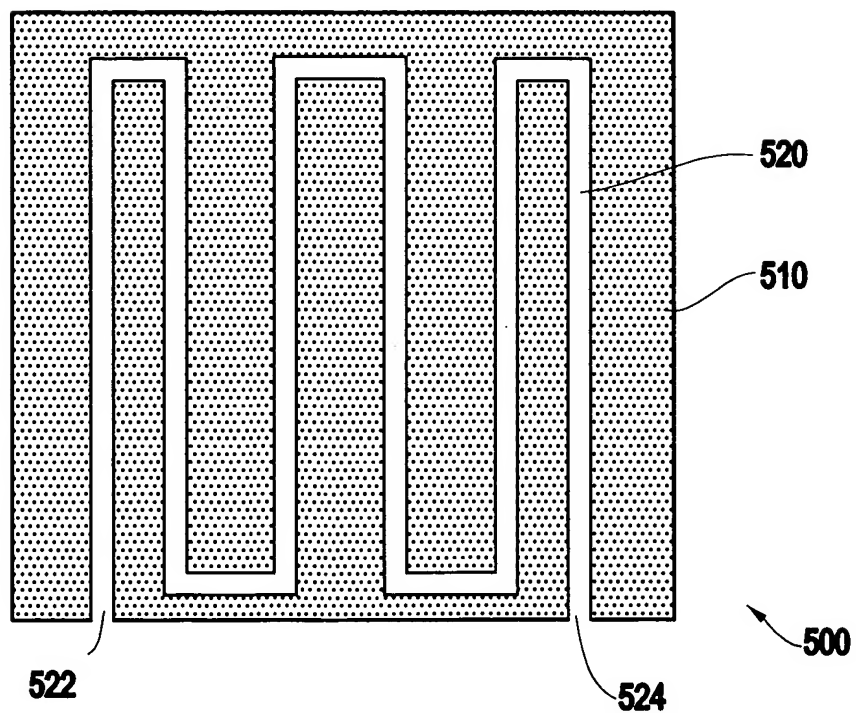


FIG.5



MATERIAL	COEFFICIENT OF THERMAL EXPANSION (PARTS PER MILLION PER DEGREE CELSIUS)	THERMAL CONDUCTIVITY (W/m K)
Pyrex	3.25	2
Borosilicate Glass (Low Expansion)	3.25	1.1
Silicon	2.6	156
Diamond	2.7	1000
SiC (Sintered)	4.4	150

FIG.6